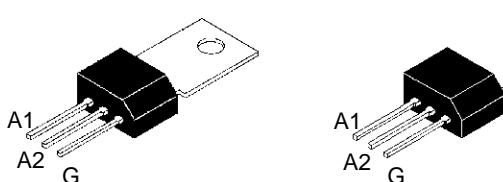


## STANDARD TRIACS

### FEATURES

- $I_T(\text{RMS}) = 4\text{A}$
- $V_{\text{DRM}} = 400\text{V}$  to  $800\text{V}$
- $I_{\text{GT}} \leq 25\text{mA}$



**TO202-1**  
(Plastic)

**Z0410xE**

**TO202-2**  
(Plastic)

**Z0410xF**

### DESCRIPTION

The Z0410xE/F series of triacs uses a high performance TOP GLASS PNPN technology. These parts are intended for general purpose switching and phase control applications.

### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value		Unit
$I_T(\text{RMS})$	RMS on-state current (360° conduction angle)		$Z0410xE/F$	$T_c = 75^\circ\text{C}$	4
			$Z0410xF$	$T_a = 25^\circ\text{C}$	0.95
$I_{TSM}$	Non repetitive surge peak on-state current ( $T_j$ initial = $25^\circ\text{C}$ )		$tp = 8.3\text{ ms}$	22	A
			$tp = 10\text{ ms}$	20	
$I^2t$	$I^2t$ Value for fusing		$tp = 10\text{ ms}$	2	$\text{A}^2\text{s}$
$di/dt$	$di/dt$ Critical rate of rise of on-state current $I_G = 50\text{ mA}$ $di/dt = 0.1\text{ A}/\mu\text{s}$ .		Repetitive $F = 50\text{ Hz}$	10	$\text{A}/\mu\text{s}$
			Non Repetitive	50	
$T_{\text{stg}}$ $T_j$	Storage and operating junction temperature range		-40, +150 -40, +125		$^\circ\text{C}$
$T_I$	Maximum lead temperature for soldering during 10s at 4.5mm from case		260		$^\circ\text{C}$

Symbol	Parameter	Voltage				Unit
		D	M	S	N	
$V_{\text{DRM}}$ $V_{\text{RRM}}$	Repetitive peak off-state voltage $T_j = 125^\circ\text{C}$	400	600	700	800	V

## Z0410xE/F

### THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
Rth(j-a)	Junction to ambient	Z0410xE	80
		Z0410xF	100
Rth(j-c)	Junction to case for D.C	10	°C/W
Rth(j-c)	Junction to case for A.C 360° conduction angle (F=50Hz)	7.5	°C/W

### GATE CHARACTERISTICS (maximum values)

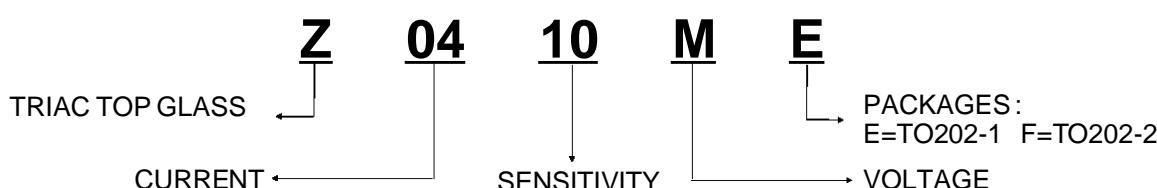
P<sub>G (AV)</sub>= 0.2 W P<sub>GM</sub> = 3 W (tp = 20 μs) I<sub>GM</sub> = 1.2 A (tp = 20 μs)

### ELECTRICAL CHARACTERISTICS

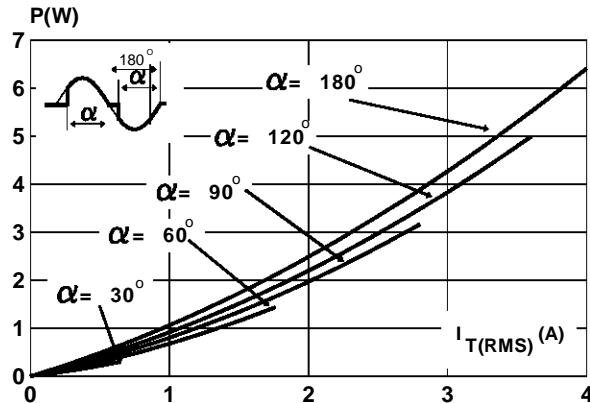
Symbol	Test Conditions	Quadrant		Sensitivity	Unit
				10	
I <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> = 25°C	I-II-III-IV	MAX	25
V <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> = 25°C	I-II-III-IV	MAX	1.5
V <sub>GD</sub>	V <sub>D</sub> =V <sub>DRM</sub> R <sub>L</sub> =3.3kΩ	T <sub>j</sub> = 125°C	I-II-III-IV	MIN	0.2
tgt	V <sub>D</sub> =V <sub>DRM</sub> I <sub>G</sub> = 40mA I <sub>T</sub> = 5.5A dI <sub>G</sub> /dt = 0.5A/μs	T <sub>j</sub> = 25°C	I-II-III-IV	TYP	2
I <sub>H</sub> *	I <sub>T</sub> = 50 mA Gate open	T <sub>j</sub> = 25°C		MAX	25
I <sub>L</sub>	I <sub>G</sub> = 1.2 I <sub>GT</sub>	T <sub>j</sub> = 25°C	I-III-IV	TYP	25
			II	TYP	50
V <sub>TM</sub> *	I <sub>TM</sub> = 5.5A tp= 380μs	T <sub>j</sub> = 25°C		MAX	2
I <sub>DRM</sub> I <sub>RRM</sub>	V <sub>D</sub> = V <sub>DRM</sub> V <sub>R</sub> = V <sub>RRM</sub>	T <sub>j</sub> = 25°C		MAX	5
		T <sub>j</sub> = 110°C		MAX	200
dV/dt *	VD=67%V <sub>DRM</sub> Gate open	T <sub>j</sub> = 110°C		MIN	200
				TYP	400
(dV/dt)c *	(dI/dt)c = 1.8 A/ms	T <sub>j</sub> = 110°C		MIN	5
					V/μs

\* For either polarity of electrode A<sub>2</sub> voltage with reference to electrode A<sub>1</sub>

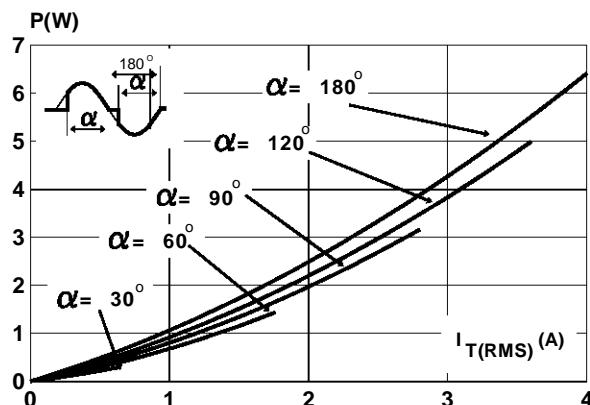
### ORDERING INFORMATION



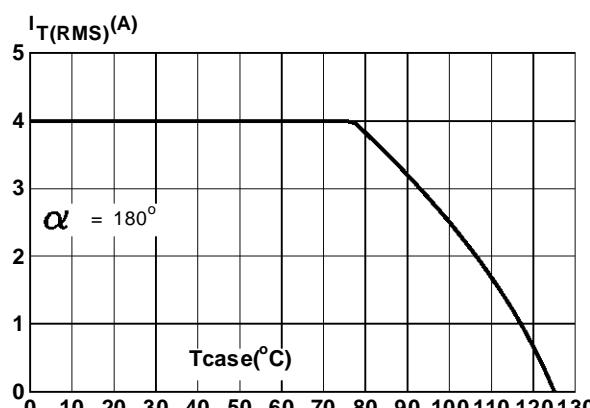
**Fig.1 :** Maximum RMS power dissipation versus RMS on-state current.



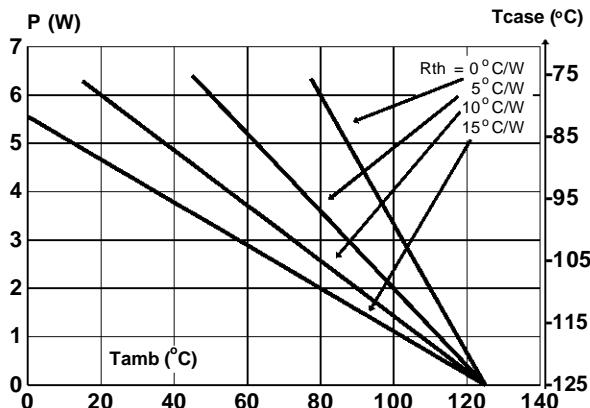
**Fig.3 :** Maximum RMS power dissipation versus RMS on-state current.



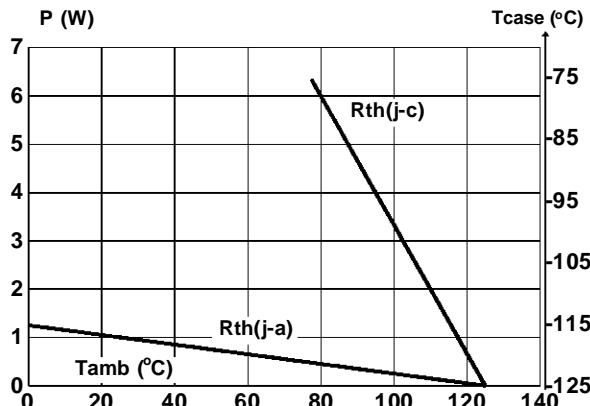
**Fig.5 :** RMS on-state current versus case temperature (TO202-1).



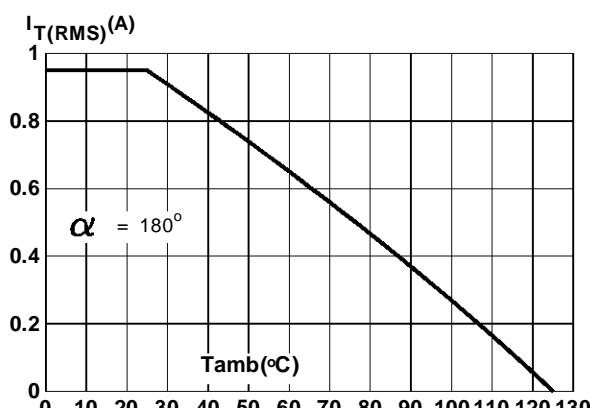
**Fig.2 :** Correlation between maximum RMS power dissipation and maximum allowable temperature (Tamb and Tcase) for different thermal resistances heatsink + contact (TO202-1).



**Fig.4 :** Correlation between maximum RMS power dissipation and maximum allowable temperature (Tamb and Tcase) (TO202-2).

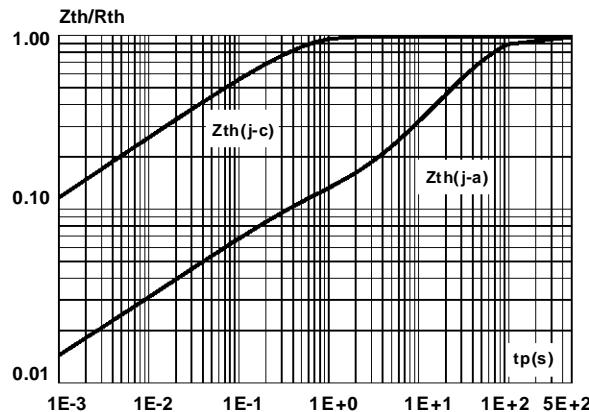


**Fig.6 :** RMS on-state current versus case temperature (TO202-2).

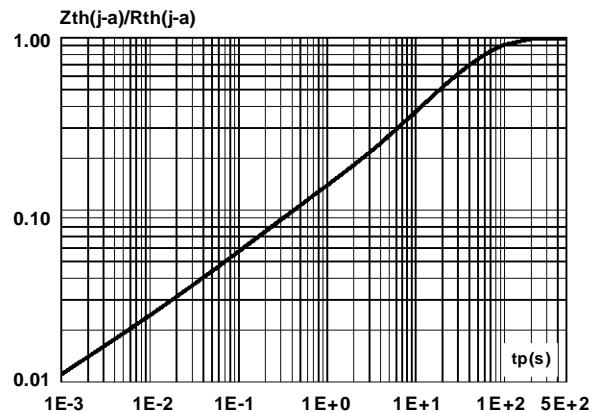


## Z0410xE/F

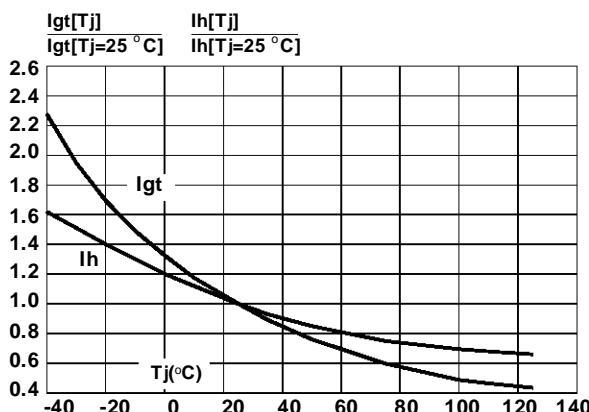
**Fig.6 :** Relative variation of thermal impedance versus pulse duration (TO202-1).



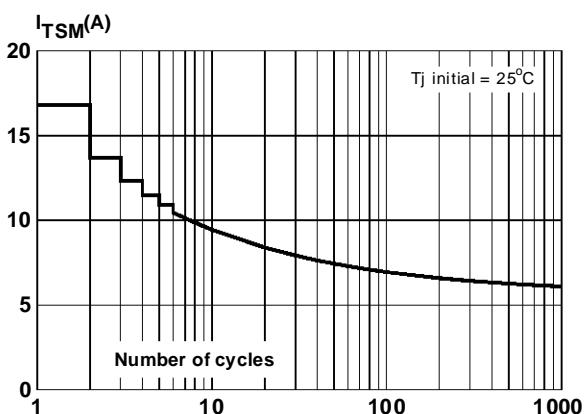
**Fig.7 :** Relative variation of thermal impedance junction to ambient versus pulse duration (TO202-2).



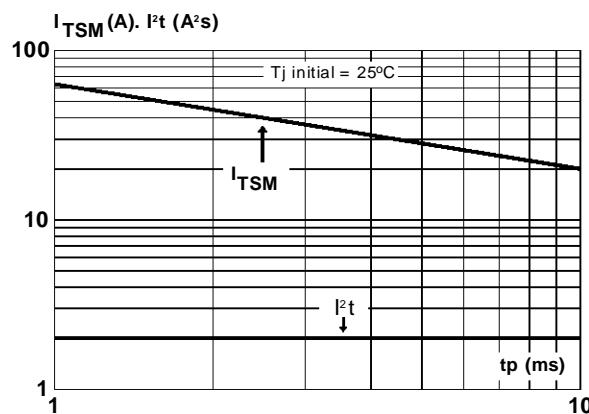
**Fig.9 :** Relative variation of gate trigger current and holding current versus junction temperature.



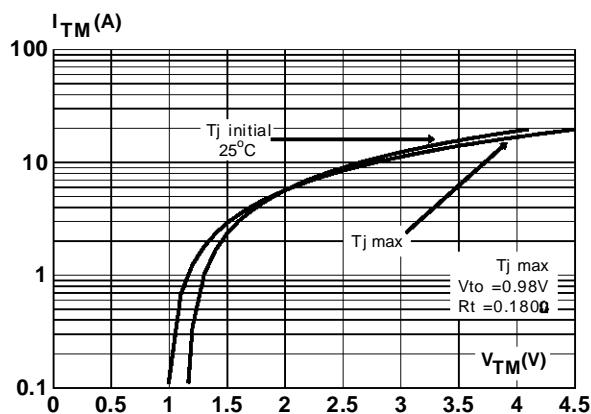
**Fig.10 :** Non repetitive surge peak on-state current versus number of cycles.



**Fig.11 :** Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $tp \leq 10ms$ , and corresponding value of  $I^2t$ .



**Fig.12 :** On-state characteristics (maximum values).



**PACKAGE MECHANICAL DATA**  
TO202-1 (Plastic)

REF.	DIMENSIONS					
	Millimeters			Inches		
	Typ.	Min.	Max.	Typ.	Min.	Max.
A			10.1			0.398
B	13.7			0.540		
C	7.3			0.287		
D	10.5			0.413		
F			1.5			0.059
G	3.2			0.126		
H	0.51			0.020		
I		3.16	3.20		0.124	0.126
J	1.5			0.059		
M	4.5			0.177		
N			5.3			0.209
N1	2.54			0.100		
O			1.4			0.055
P			0.7			0.028

Marking : type number

Weight : 1.4 g

## Z0410xE/F

### PACKAGE MECHANICAL DATA TO202-2 (Plastic)

REF.	DIMENSIONS					
	Millimeters			Inches		
	Typ.	Min.	Max.	Typ.	Min.	Max.
A			10.1			0.398
B	1.2			0.047		
C	7.3			0.287		
D	10.5			0.413		
E	7.4			0.290		
F			1.5			0.059
H	0.51			0.020		
J	1.5			0.059		
M	4.5			0.177		
N			5.3			0.209
N1	2.54			0.100		
O			1.4			0.055
P			0.7			0.028

Marking : type number

Weight : 1.0 g

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